

FIG. 1

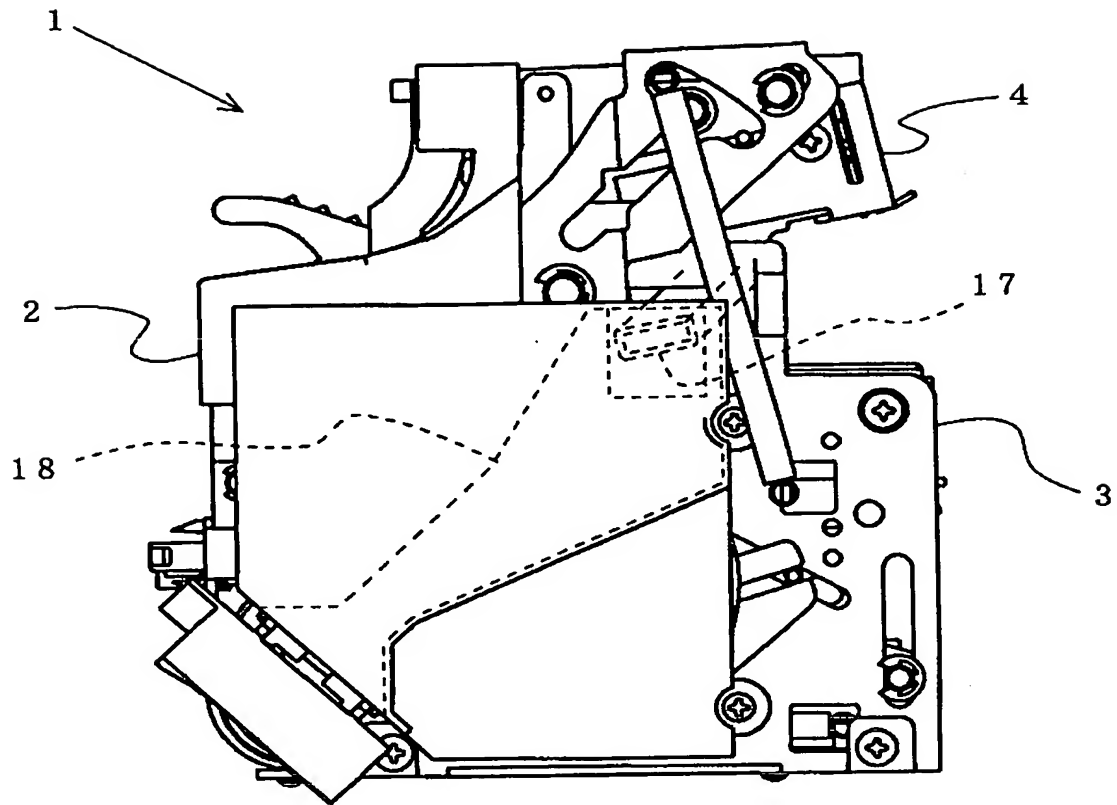


FIG.2

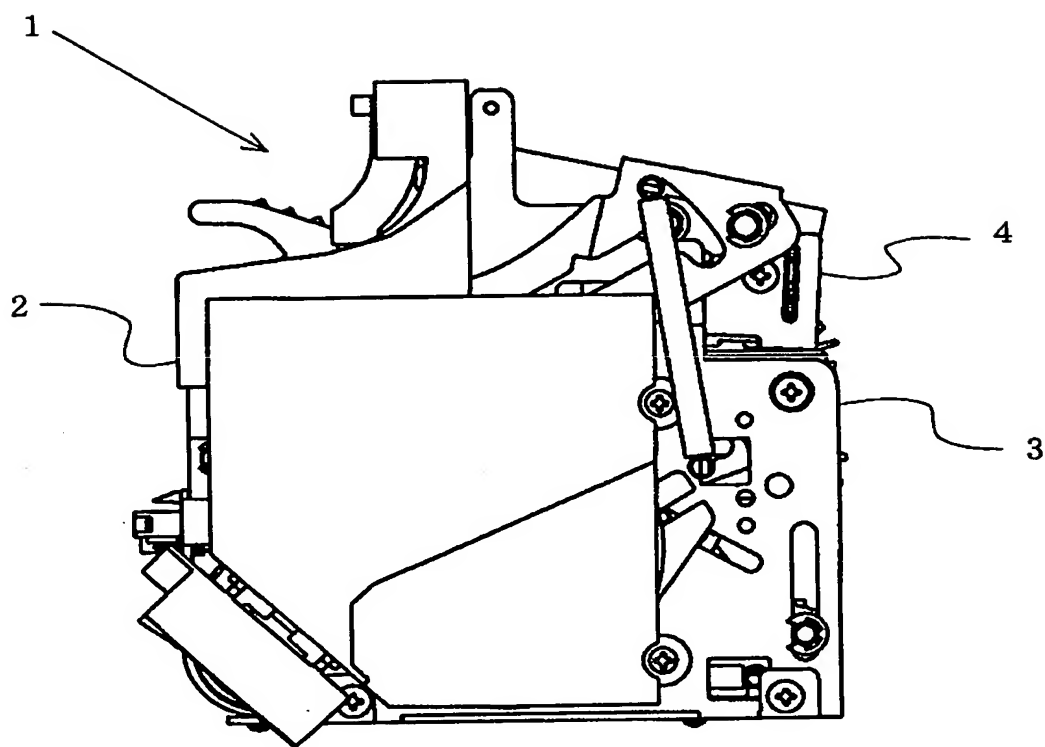


FIG.3

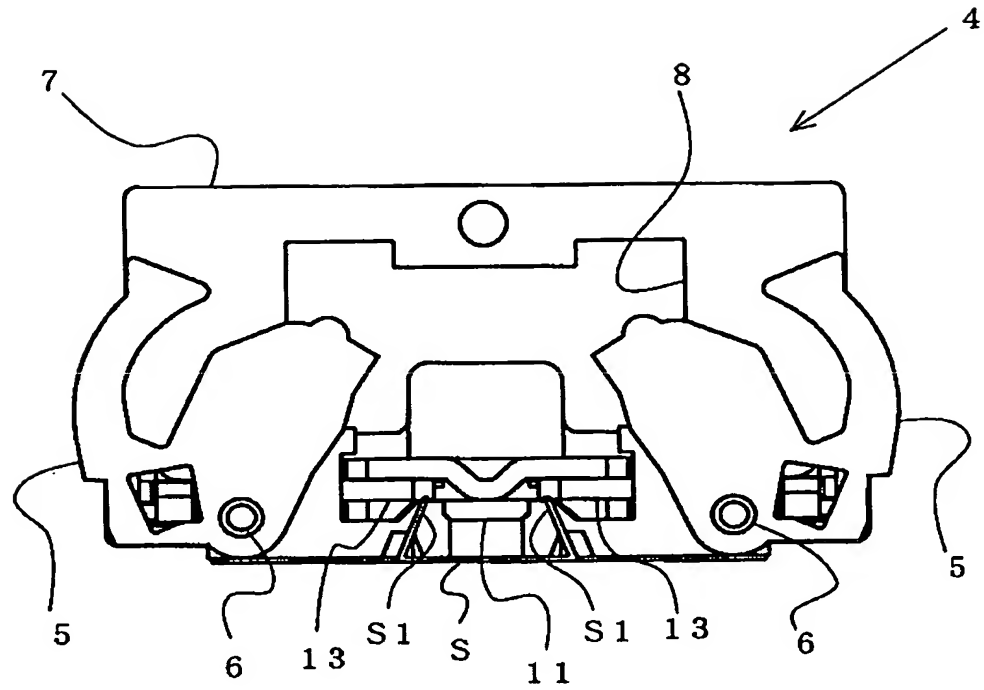


FIG.4

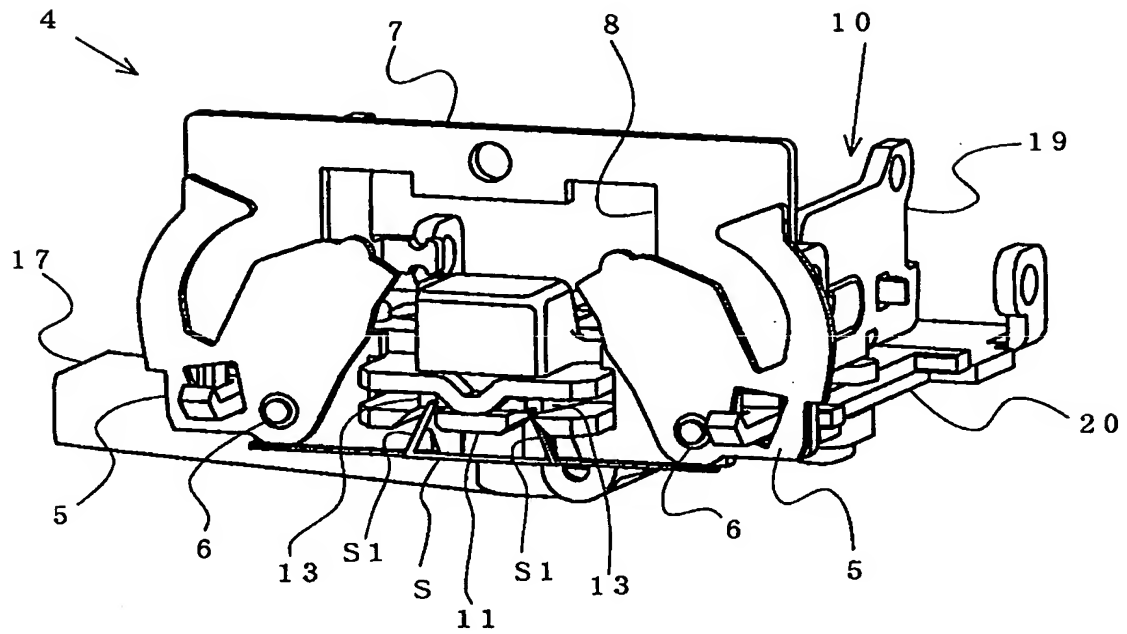


FIG.5

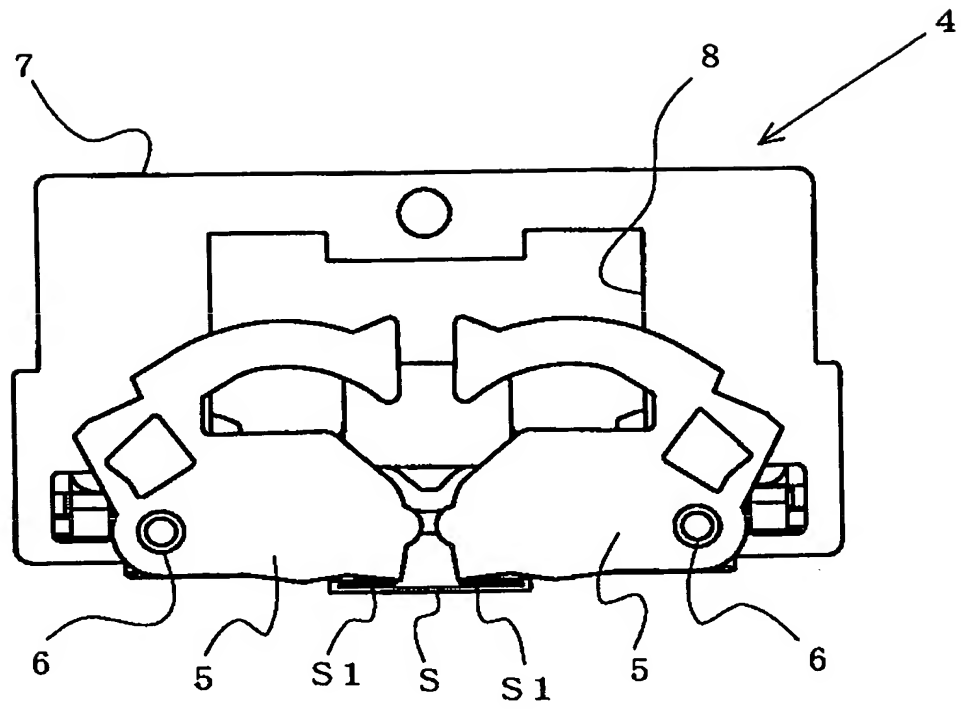


FIG. 6

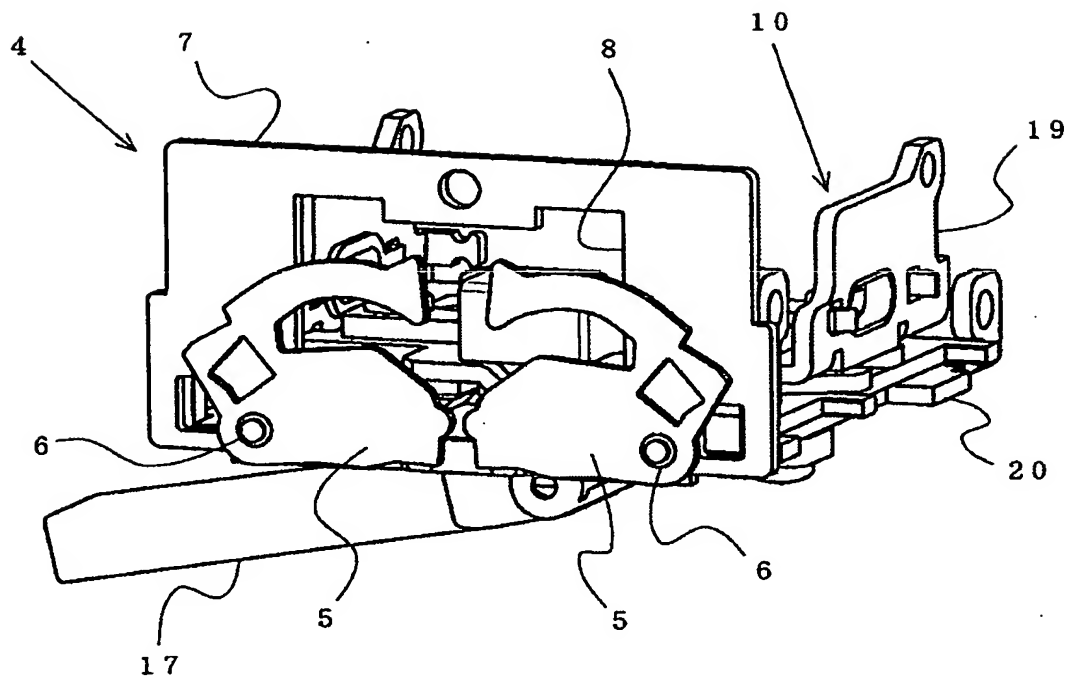


FIG. 7

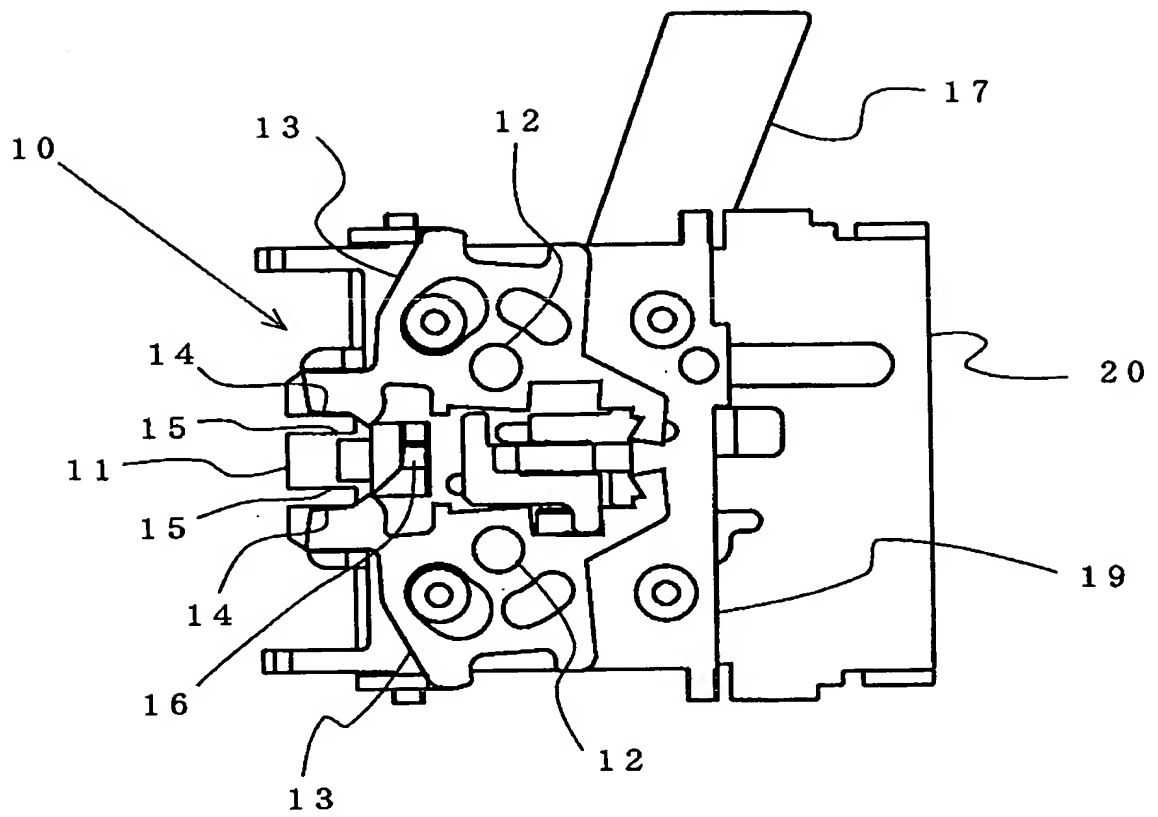


FIG. 8

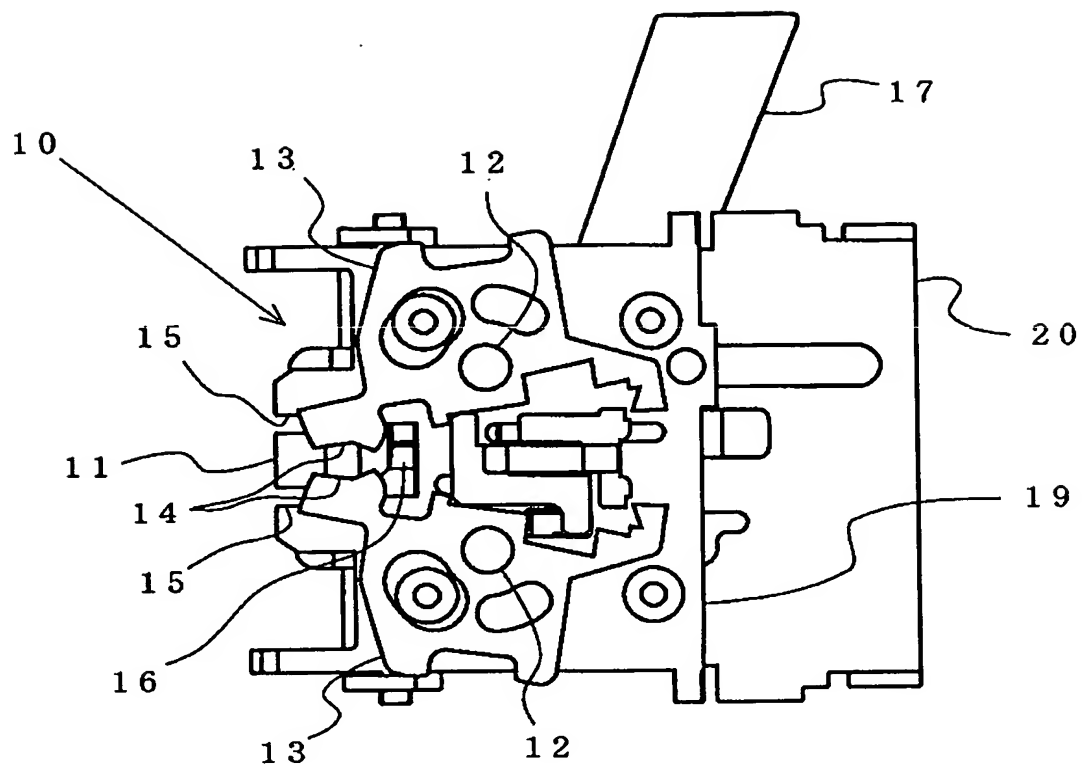
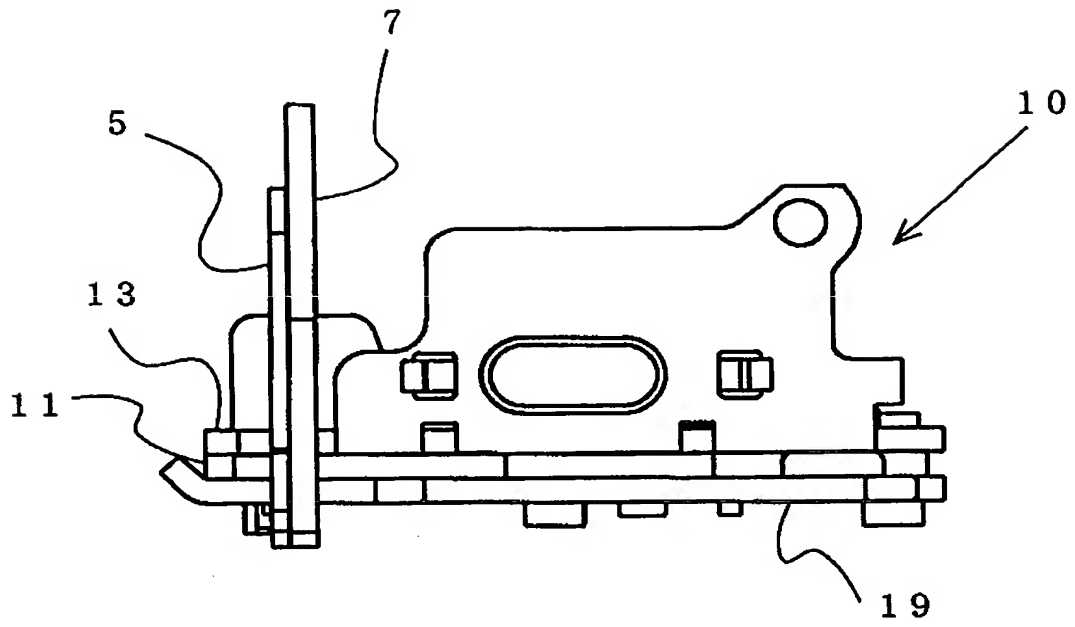


FIG. 9



This diagram shows an exploded perspective view of a multi-layer printed circuit board assembly. The assembly consists of several layers and components, labeled with reference numerals:

- 11**: A central component, possibly a microchip or a small module, mounted on the top layer.
- 12**: The top layer of the printed circuit board, featuring various circular vias and mounting pads.
- 13**: A middle layer or a separate component that interfaces with the top and bottom layers.
- 14**: A bottom layer or another component, also featuring circular vias and mounting pads.
- 16**: A vertical component, likely a connector or a stand-off, positioned between the top and bottom layers.
- 17**: A large, rectangular base or support structure that the entire assembly is mounted on.
- 19**: A component or layer located between the base structure and the main circuit board assembly.
- 20**: The bottom-most layer or a component of the assembly.

The diagram illustrates the spatial relationship and alignment of these components, showing how they fit together to form a complete electronic assembly.

FIG. 11

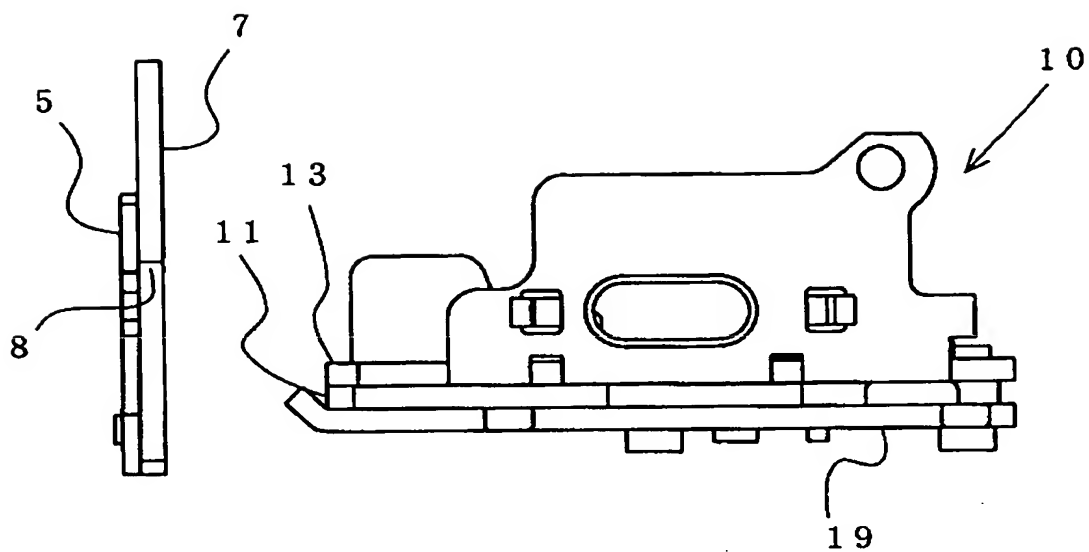


FIG. 12

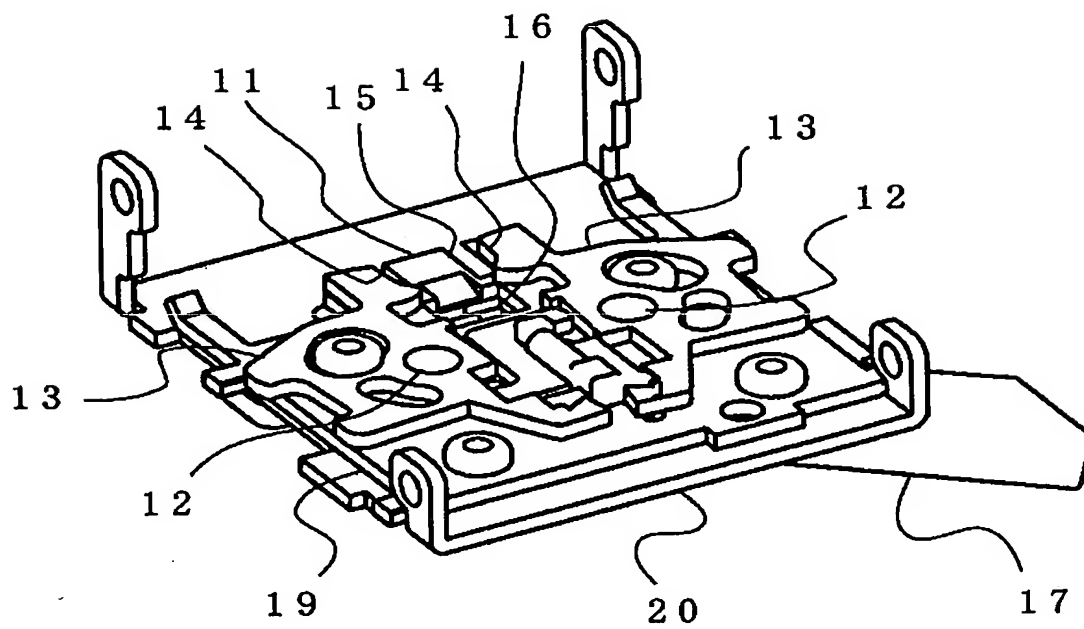


FIG. 13

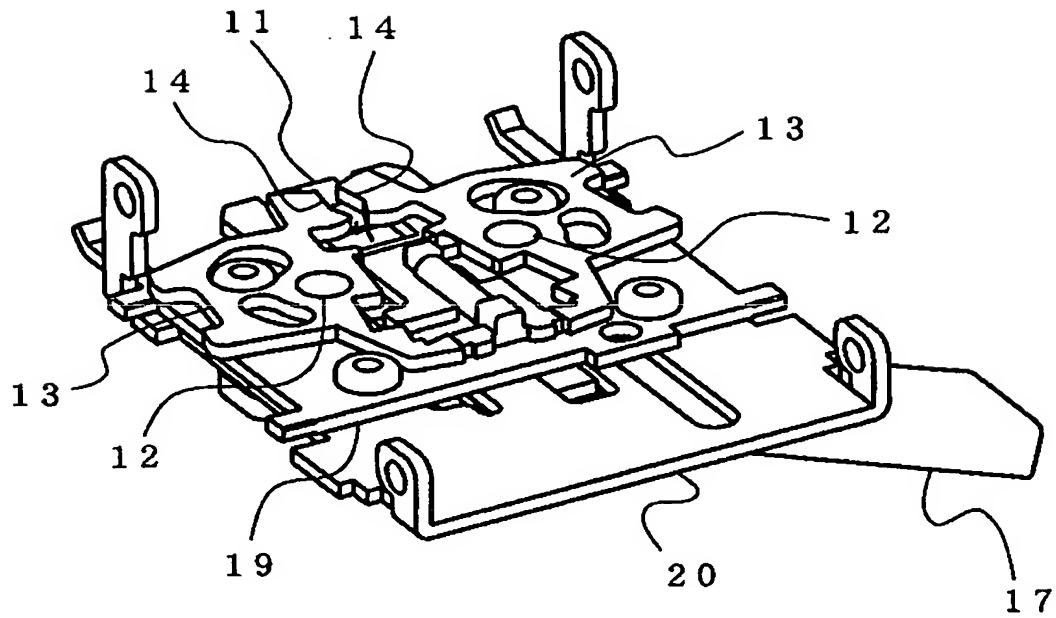


FIG. 14

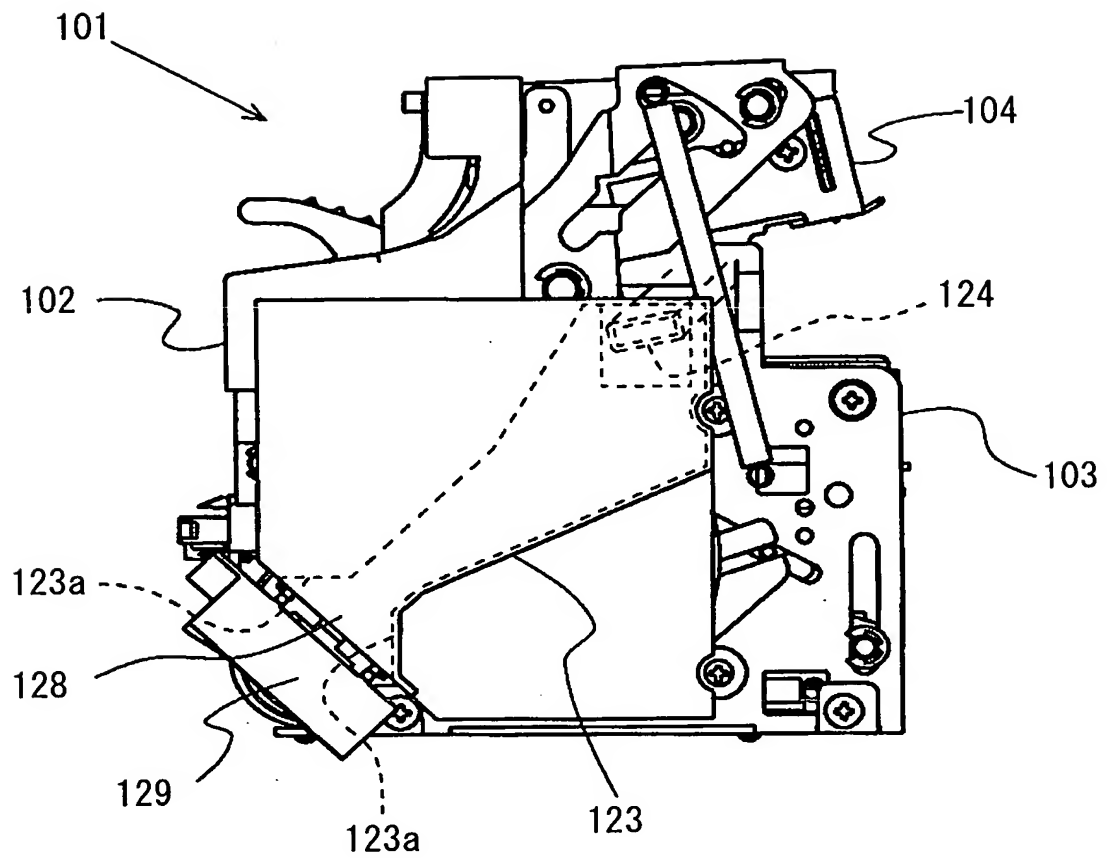


FIG. 15

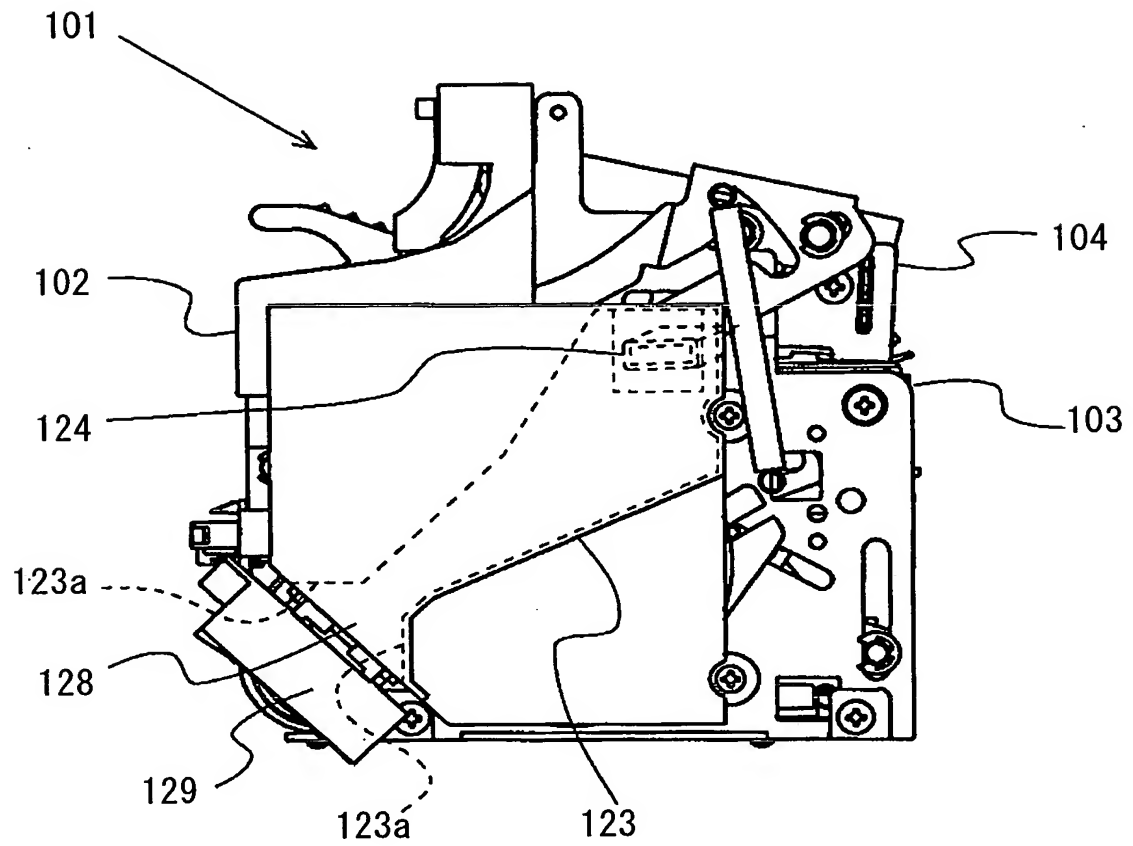


FIG. 16

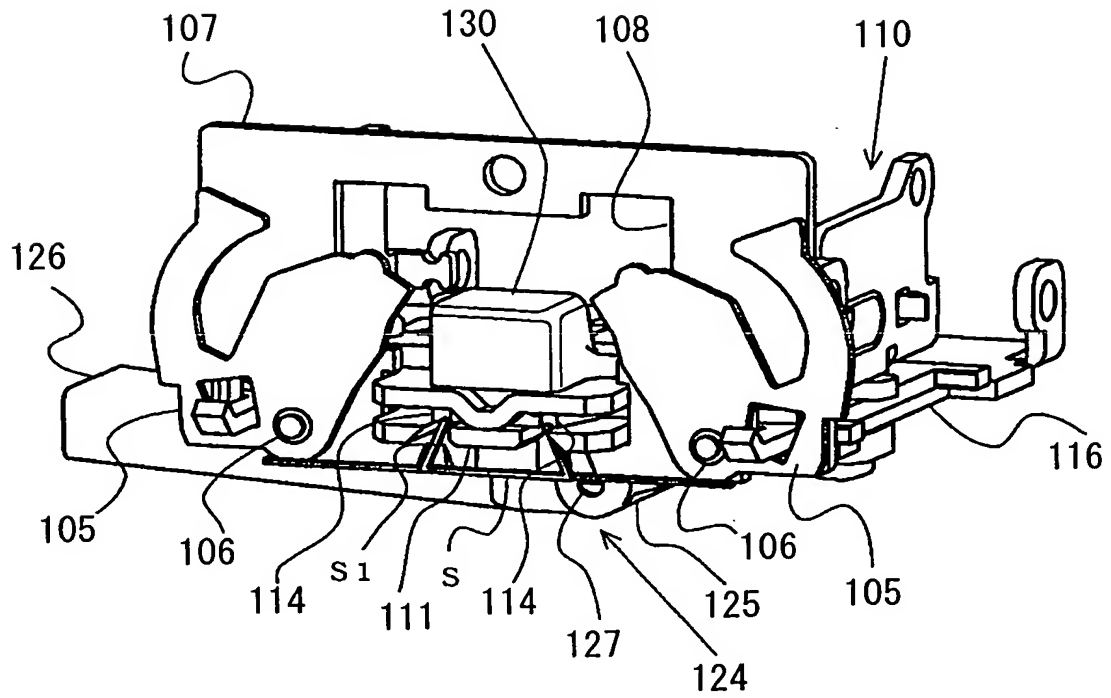


FIG. 17

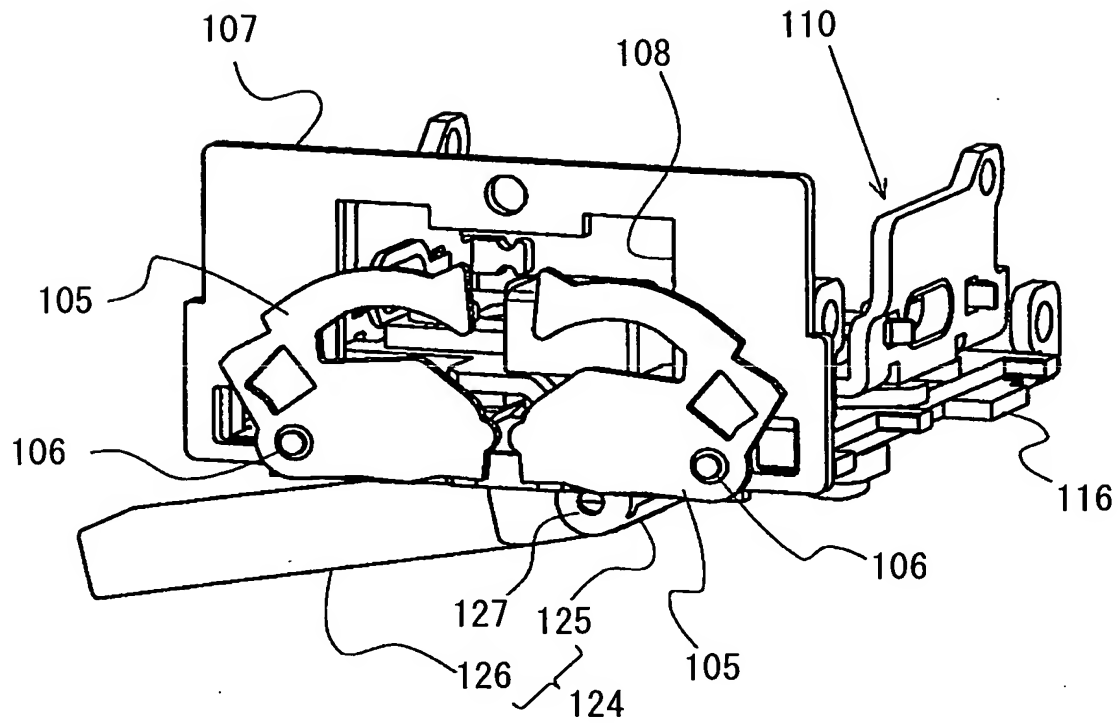


FIG. 18

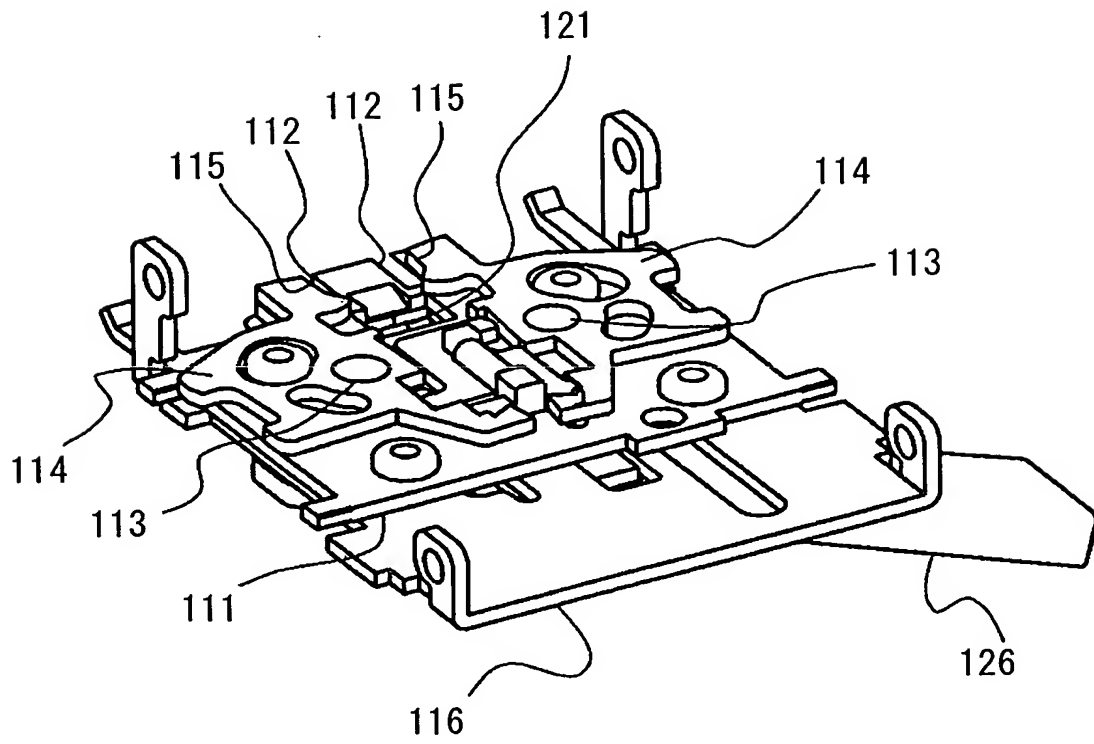


FIG. 19

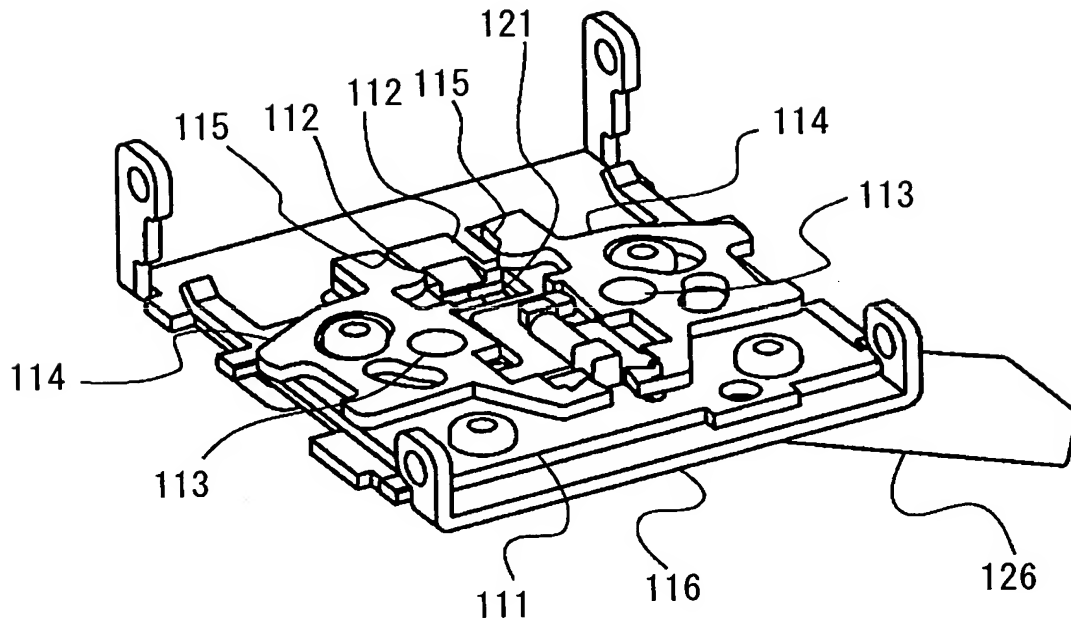


FIG. 20

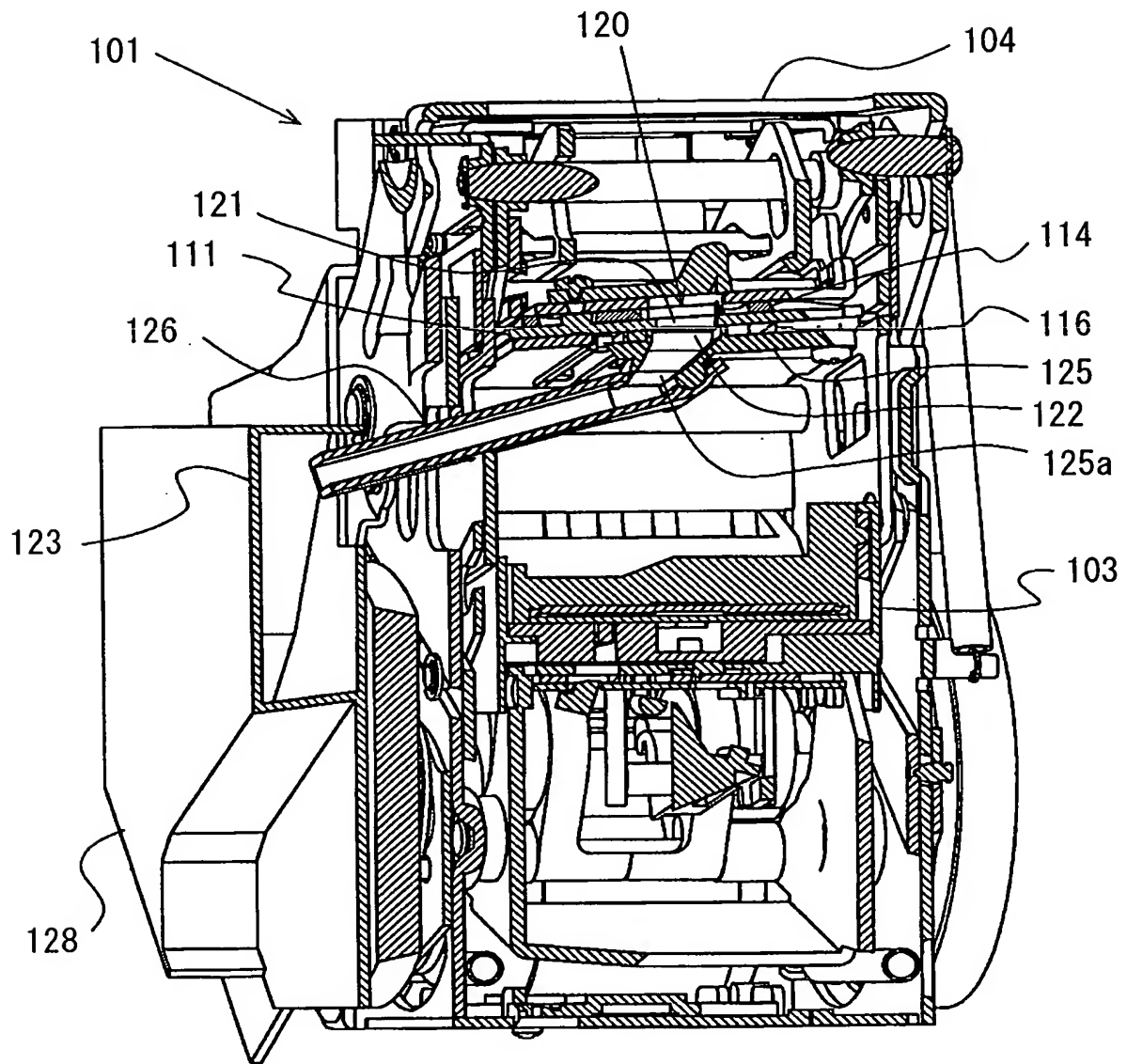


FIG.21

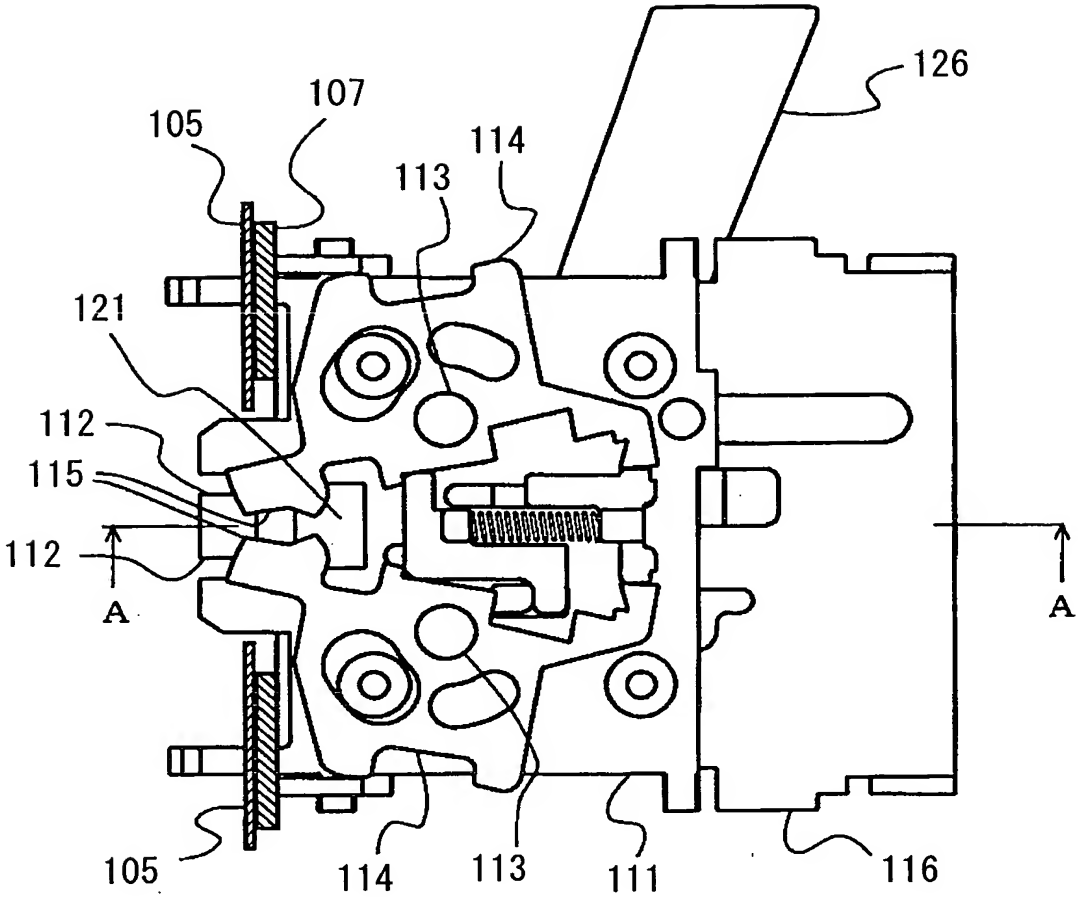


FIG.22

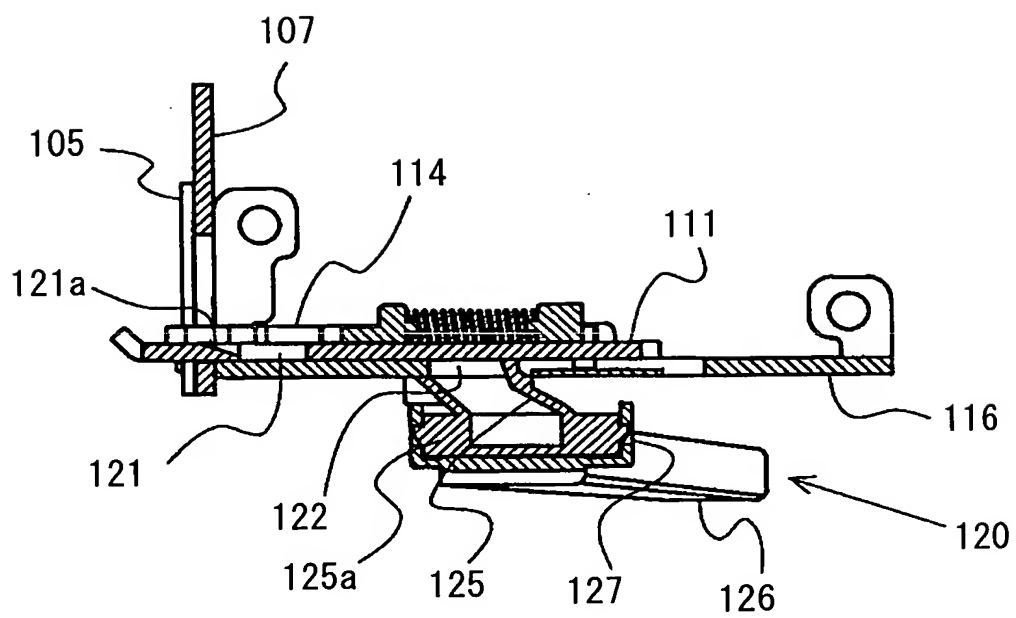


FIG.23

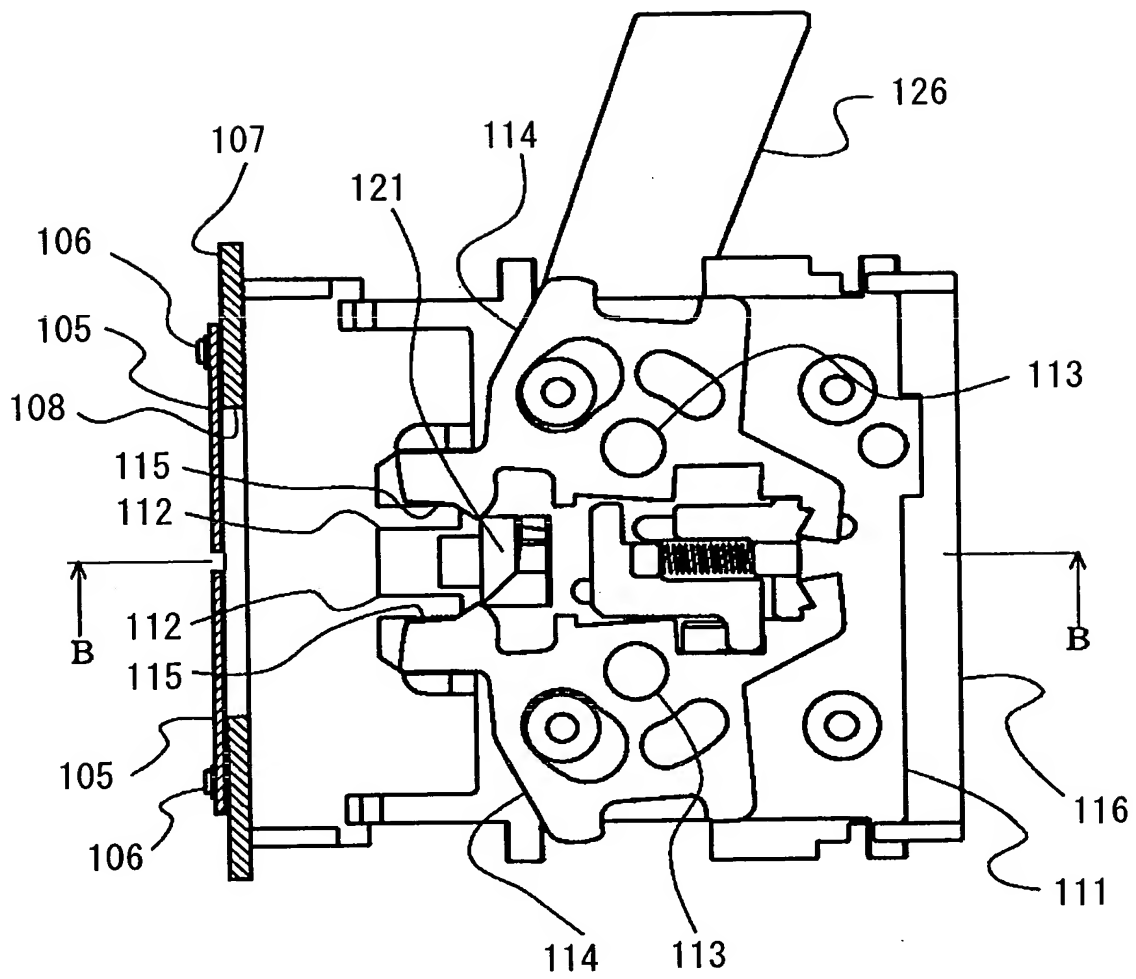


FIG.24

